



Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	27-11-2018
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H755ZIT6	461A*450XXXV	A	9998	27-11-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LQFP	20X20X1.4	200		
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	461A*450XXV				6999999.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	16.439	mg	supplier	die	Silicon (Si)	7440-21-3		15.697	mg	954863	11937
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5353	67
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	16789	210
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	61	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2737	34
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	487	6
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	61	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	19648	246
LEADFRAME (ALS -C7025)	Copper and its alloy	240.186	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		231.059	mg	962000	175711
				supplier	ALLOY	Nickel (Ni)	7440-02-0		7.206	mg	30000	5480
				supplier	ALLOY	Silicon (Si)	7440-21-3		1.561	mg	6500	1187
				supplier	ALLOY	Magnesium (Mg)	7439-95-4		0.360	mg	1500	274
LEADFRAME (ALS - Ag Plating)	M-011 Other inorganic materials	1.280	mg	supplier	COATING	Silver(Ag)	7440-22-4		1.280	mg	1000000	974
DIE ATTACH (Evertech -AP4200)	M-011 Other inorganic materials	2.452	mg	supplier	GLUE	Formaldehyde, oligomeric reaction products w	9003-36-5		0.392	mg	160000	298
				supplier	GLUE	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8		0.037	mg	15000	28
				supplier	GLUE	Formaldehyde, oligomeric reaction products w	9003-35-4		0.037	mg	15000	28
				supplier	GLUE	2-butoxyethyl acetate	112-07-2		0.098	mg	40000	75
BONDING WIRE (MKE - Au HTS 2N)	M-011 Other inorganic materials	3.008	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		2.979	mg	990480	2265
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.029	mg	9500	22
				supplier	BONDING WIRE	Calcium (Ca)	7440-70-2		0.000	mg	20	0
ENCAPSULATION (Sumitomo - G631S)	M-011 Other inorganic materials	1043.777	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		10.445	mg	10000	7943
				supplier	MOLDING COMPOUND	Epoxy Resin B	Proprietary		10.445	mg	10000	7943
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		52.226	mg	50000	39716
				supplier	MOLDING COMPOUND	Silica(Amorphous) A	60676-86-0		819.205	mg	785000	622969
				supplier	MOLDING COMPOUND	Silica(Amorphous) B	7631-86-9		146.233	mg	140000	111204
FINISHING (Sytron - Pure Tin)	M-011 Other inorganic materials	7.858	mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		5.223	mg	5000	3972
				supplier	COATING	Tin (Sn)	7440-31-5		7.858	mg	1000000	5976